Product / Package Information

Package	LQFP_EP
Lead Count	176
Body Size	24 X 24 X 1.4 (6.0 EP)
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.32 E+00	86.91	869100	65.67	656657
Thermosets	Epoxy and Phenol resin	Proprietary	1.94 E-01	12.78	127800	9.66	96561
Other inorganic materials	Carbon black	1333-86-4	4.71 E-03	0.31	3100	0.23	2342
Subtotal			1.52 E+00	100	1000000	75.56	755560

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.09 E-01	97.5	975000	15.36	153558
Copper & its alloys	Iron	7439-89-6	7.44 E-03	2.35	23500	0.37	3701
Copper & its alloys	Zinc	7440-66-6	3.80 E-04	0.12	1200	0.02	189
Copper & its alloys	Phosphorus	7723-14-0	9.50 E-05	0.03	300	0.00	47
Subtotal			3.17 E-01	100.00	1000000	15.75	157496

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.70 E-04	100	1000000	0.03	283

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.42 E-01	100	1000000	7.08	70809

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	5.72 E-03	99	990000	0.28	2845
Precious Metals	Palladium	7440-05-3	5.78 E-05	1	10000	0.003	29
Subtotal			5.78 E-03	100	1000000	0.29	2874

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.37 E-02	100	1000000	1.18	11781

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.77 E-03	73.54	735400	0.09	881
Other organic materials	Epoxy resin A	TS ref# 10013	1.77 E-04	7.35	73500	0.01	88
Others	Anhydride	TS ref# 10181	1.77 E-04	7.35	73500	0.01	88
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	7.08 E-05	2.94	29400	0.00	35
Other organic materials	Epoxy resin B	TS ref# 10237	7.08 E-05	2.94	29400	0.00	35
Others	Epoxy resin modifier	TS ref# 10038	7.08 E-05	2.94	29400	0.00	35
Others	Anhydride	TS ref# 10180	7.08 E-05	2.94	29400	0.00	35
Subtotal			2.41 E-03	100.00	1000000	0.12	1198

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.01 E+00**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary